for new design

LB W5SM

Golden DRAGON®





Applications

- Transportation, Plane, Ship

Features:

- Package: white SMD package, colorless clear silicone resin
- Chip technology: ThinGaN
- Typ. Radiation: 120° (Lambertian emitter)
- − Color: $λ_{dom}$ = 467 nm (• blue)
- Corrosion Robustness Class: 3B
- ESD: 8 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 3B)



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Ordering Information			
Туре	Luminous Flux $^{1)}$ $I_F = 350 \text{ mA}$ Φ_V	Ordering Code	
LB W5SM-FZHX-35	15 33 lm	Q65110A9221	



Maximum Ratings			
Parameter	Symbol		Values
Operating Temperature	T _{op}	min.	-40 °C
		max.	125 °C
Storage Temperature	T _{stg}	min.	-40 °C
	3	max.	125 °C
Junction Temperature	T_{j}	max.	135 °C
Junction Temperature for short time applications*	T _j	max.	175 °C
Forward current	I _F	min.	100 mA
$T_S = 25 ^{\circ}C$		max.	1000 mA
Surge Current	I _{FS}	max.	2500 mA
$t \le 10 \ \mu s$; D = 0.005 ; $T_s = 25 \ ^{\circ}C$			
ESD withstand voltage acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 3B)	V_{ESD}		8kV
Reverse current 2)	I _R	max.	200 mA

^{*}The median lifetime (L70/B50) for Tj =175 $^{\circ}$ C is 100h.

Characteristics

 I_F = 350 mA; T_S = 25 °C

Parameter	Symbol		Values
Peak Wavelength	$\lambda_{ m peak}$	typ.	465 nm
Dominant Wavelength 3)	$\lambda_{\sf dom}$	min.	464 nm
$I_{\rm F} = 350 \text{ mA}$	dom	typ.	467 nm
		max.	476 nm
Spectral Bandwidth at 50% I _{rel,max}	Δλ	typ.	25 nm
Viewing angle at 50 % I _V	2φ	typ.	120 °
Forward Voltage 4)	V_{F}	min.	2.70 V
$I_{\rm F} = 350 \text{ mA}$	•	typ.	3.20 V
		max.	3.70 V
Reverse voltage (ESD device)	V _{R ESD}	min.	45 V
Reverse voltage ²⁾ I _R = 20 mA	V_R	max.	1.2 V
Real thermal resistance junction/solderpoint ⁵⁾	R _{thJS real}	typ.	5 K / W
	แมวาชสเ	max.	6.4 K / W



Brightness Groups

Group	Luminous Flux ¹⁾ $I_F = 350 \text{ mA}$ min. Φ_V	Luminous Flux ¹⁾ $I_F = 350 \text{ mA}$ max. Φ_V	Luminous Intensity $^{6)}$ $I_F = 350 \text{ mA}$ typ. I_V
FZ	15 lm	18 lm	05 cd
GX	18 lm	21 lm	06 cd
GY	21 lm	24 lm	07 cd
GZ	24 lm	28 lm	09 cd
HX	28 lm	33 lm	10 cd

Wavelength Groups

Group	Dominant Wavelength $^{3)}$ $I_F = 350 \text{ mA}$ min. λ_{dom}	Dominant Wavelength $^{3)}$ $I_F = 350 \text{ mA}$ max. λ_{dom}
3	464 nm	468 nm
4	468 nm	472 nm
5	472 nm	476 nm



Group Name on Label

Example: FZ-3

Brightness Wavelength

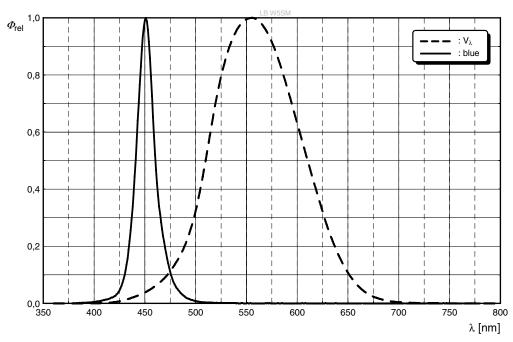
3

FZ



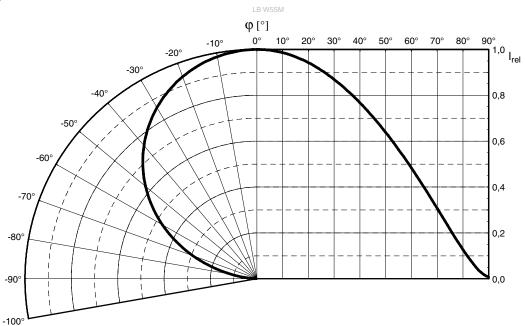
Relative Spectral Emission 6)

 I_{rel} = f (λ); I_F = 350 mA; T_S = 25 °C



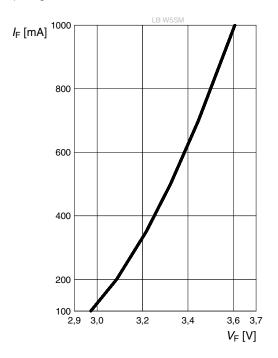
Radiation Characteristics 6)

 $I_{rel} = f (\phi); T_S = 25 \, ^{\circ}C$



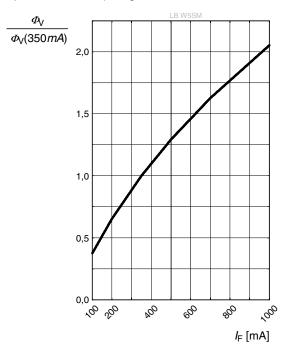
Forward current 6), 7)

$$I_F = f(V_F); T_S = 25 \, ^{\circ}C$$



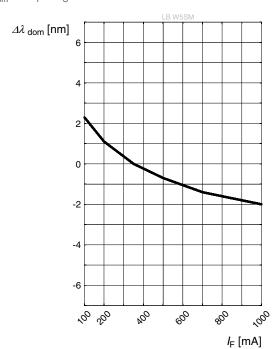
Relative Luminous Flux 6), 7)

$$\Phi_{V}/\Phi_{V}(350 \text{ mA}) = f(I_{F}); T_{S} = 25 \text{ }^{\circ}\text{C}$$



Dominant Wavelength 6)

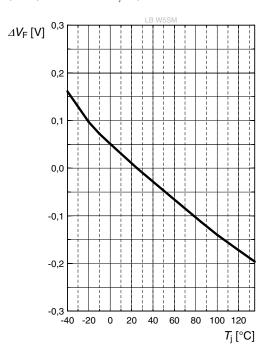
$$\Delta\lambda_{dom} = f(I_F); T_S = 25 \text{ }^{\circ}\text{C}$$





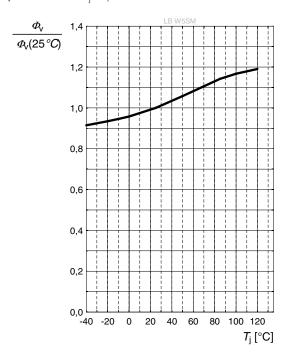
Forward Voltage 6)

$$\Delta V_F = V_F - V_F (25 \ ^{\circ}C) = f(T_j); I_F = 350 \ mA$$



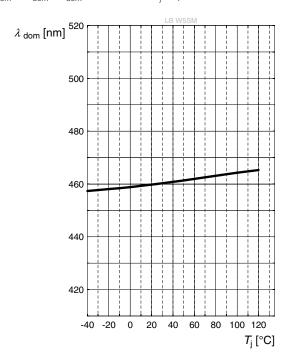
Relative Luminous Flux 6)

$$\Phi_{V}/\Phi_{V}(25 \text{ °C}) = f(T_{i}); I_{F} = 350 \text{ mA}$$



Dominant Wavelength 6)

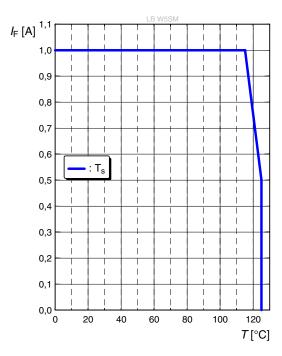
$$\Delta \lambda_{\text{dom}} = \lambda_{\text{dom}} - \lambda_{\text{dom}} (25 \text{ °C}) = f(T_j); I_F = 350 \text{ mA}$$





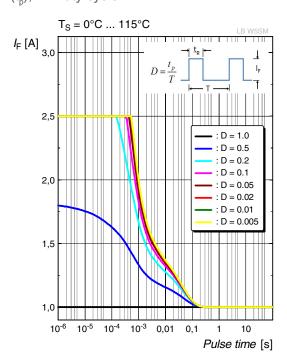
Max. Permissible Forward Current

 $I_F = f(T)$



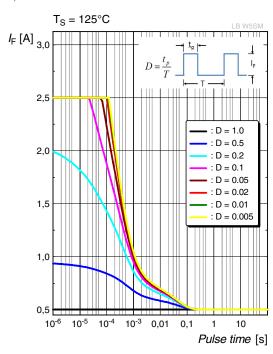
Permissible Pulse Handling Capability

 $I_F = f(t_p)$; D: Duty cycle



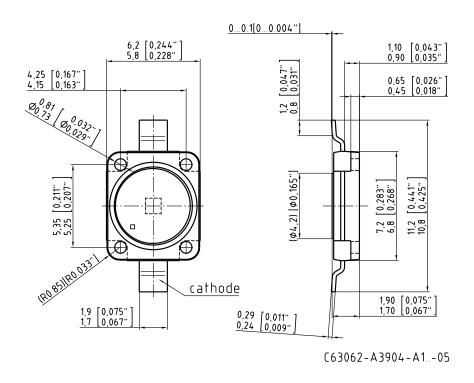
Permissible Pulse Handling Capability

 $I_F = f(t_p)$; D: Duty cycle





Dimensional Drawing 8)



Approximate Weight: 218.0 mg

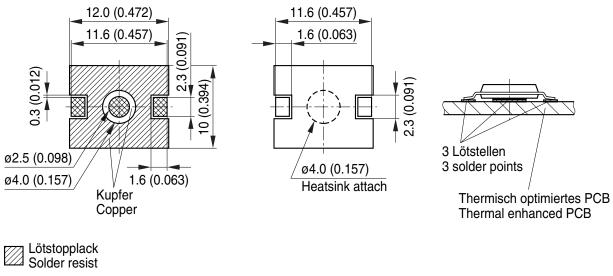
Corrosion test: Class: 3B

Test condition: 40°C / 90 % RH / 15 ppm H₂S / 14 days (stricter then IEC

60068-2-43)

ESD advice: LED is protected by ESD device which is connected in paralell to LED-Chip.

Recommended Solder Pad 8)



Lötpasten Schablone Solder paste stencil

Bare Copper Freies Kupfer

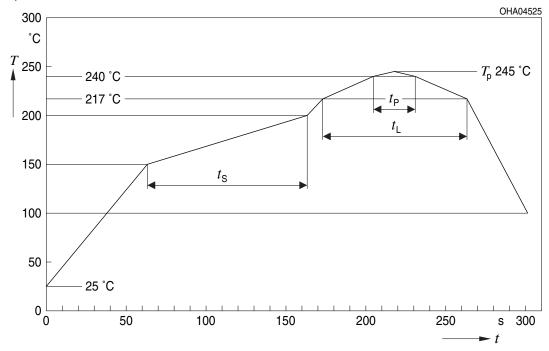
OHAY0681

For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere. Package not suitable for ultra sonic cleaning.



Reflow Soldering Profile

Product complies to MSL Level 2 acc. to JEDEC J-STD-020D.01

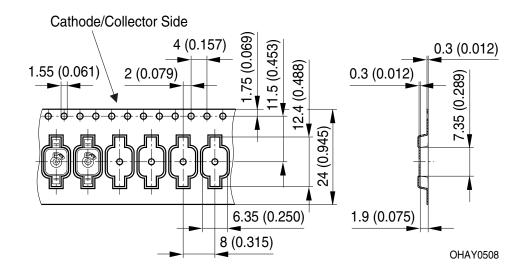


Profile Feature	Symbol	Symbol Pb-Free (SnAgCu) Assembly			Unit
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat*) 25 °C to 150 °C			2	3	K/s
Time t_s T_{Smin} to T_{Smax}	t _s	60	100	120	S
Ramp-up rate to peak*) $T_{\rm Smax}$ to $T_{\rm P}$			2	3	K/s
Liquidus temperature	T_L		217		°C
Time above liquidus temperature	$t_{\scriptscriptstyle \perp}$		80	100	S
Peak temperature	T _P		245	260	°C
Time within 5 °C of the specified peak temperature T _p - 5 K	t _P	10	20	30	S
Ramp-down rate* T _P to 100 °C			3	6	K/s
Time 25 °C to T _P				480	S

All temperatures refer to the center of the package, measured on the top of the component * slope calculation DT/Dt: Dt max. 5 s; fulfillment for the whole T-range

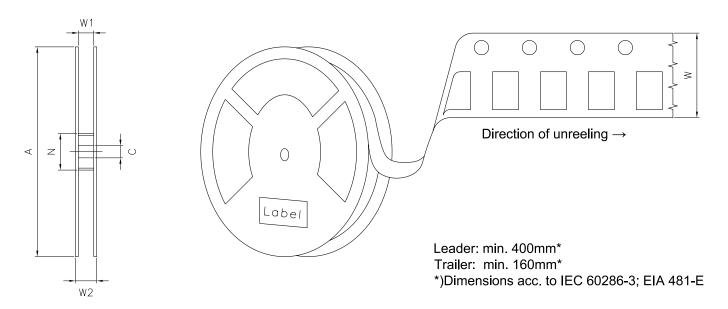


Taping 8)





Tape and Reel 9)



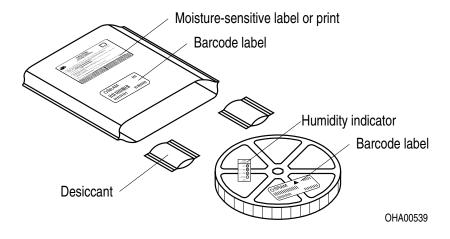
Reel dimensions [mm]

A	W	N_{\min}	W_1	$W_{2 \text{ max}}$	Pieces per PU
180 mm	24 + 0.3 / - 0.1	60/100	24.4 + 2	30.4	800

Barcode-Product-Label (BPL)



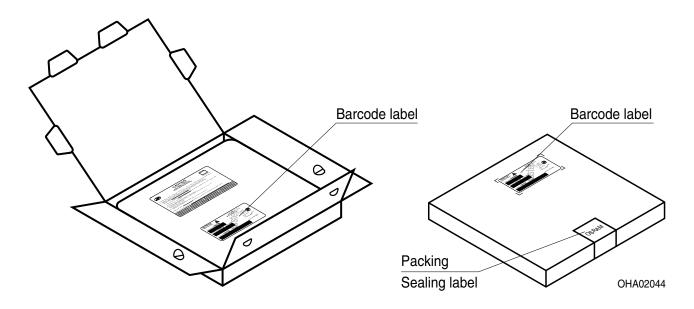
Dry Packing Process and Materials 8)



Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.



Transportation Packing and Materials 8)

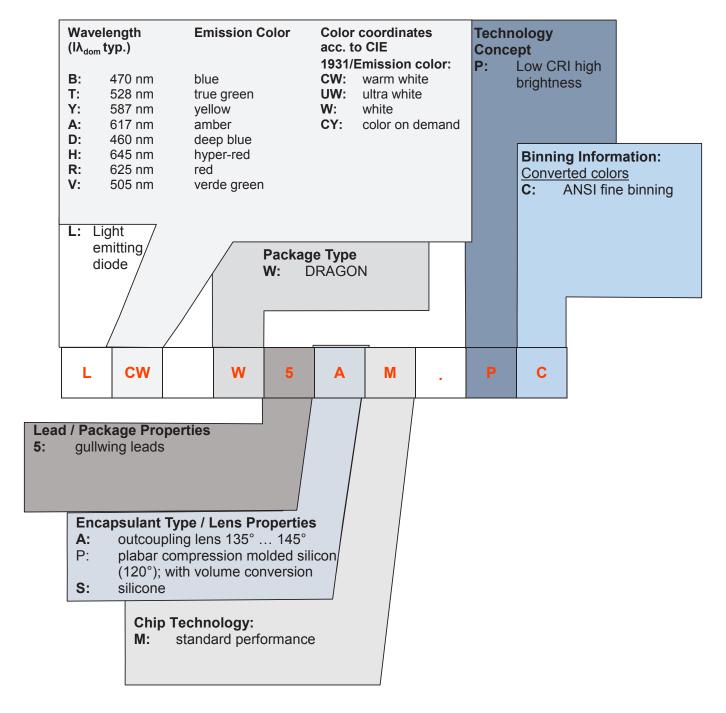


Dimensions of transportation box in mm

Width	Length	Height
195 ± 5 mm	195 ± 5 mm	42 ± 5 mm



Type Designation System





Notes

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the LED specified in this data sheet fall into the class moderate risk (exposure time 0.25 s). Under real circumstances (for exposure time, eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. As is also true when viewing other bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this LED contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize LED exposure to aggressive substances during storage, production, and use. LEDs that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related informations please visit www.osram-os.com/appnotes



Disclaimer

Disclaimer

Language english will prevail in case of any discrepancies or deviations between the two language wordings.

Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version on the OSRAM OS webside.

Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest

By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

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Glossary

- Brightness: Brightness values are measured during a current pulse of typically 25 ms, with an internal reproducibility of ±8 % and an expanded uncertainty of ±11 % (acc. to GUM with a coverage factor of
- Reverse Operation: Reverse Operation of 10 hours is permissible in total. Continuous reverse operation is not allowed.
- 3) Wavelength: The wavelength is measured at a current pulse of typically 25 ms, with an internal reproducibility of ±0.5 nm and an expanded uncertainty of ±1 nm (acc. to GUM with a coverage factor of k = 3).
- Forward Voltage: The forward voltage is measured during a current pulse of typically 8 ms, with an internal reproducibility of ±0.05 V and an expanded uncertainty of ±0.1 V (acc. to GUM with a coverage factor of k = 3).
- 5) **Thermal Resistance**: Rth max is based on statistic values (6σ).
- 6) Typical Values: Due to the special conditions of the manufacturing processes of LED, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- Characteristic curve: In the range where the line of the graph is broken, you must expect higher differences between single LEDs within one packing unit.
- Tolerance of Measure: Unless otherwise noted in drawing, tolerances are specified with ±0.1 and dimensions are specified in mm.
- Tape and Reel: All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.



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